

Title (en)  
PROCESS FOR MOLDING A FRICTION WAFER

Title (de)  
VERFAHREN ZUM FORMEN EINER FRIKTIONSSCHEIBE

Title (fr)  
PROCESSUS DE MOULAGE D UNE TRANCHE À FRICTION

Publication  
**EP 2344690 A1 20110720 (EN)**

Application  
**EP 08816678 A 20081008**

Priority  
US 2008011571 W 20081008

Abstract (en)  
[origin: WO2010042087A1] A process and apparatus for making die-dried friction wafers collects friction particulates in a mold defining a wafer. The mold includes at least one perforate wall portion against which an aqueous slurry including the particulates is passed to form at least one layer on the wall as the particulates collect in the mold. The collection is dried followed by curing, and may be cured in the mold by heating.

IPC 8 full level  
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CPC (source: EP)  
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DOCDB simple family (publication)  
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